



## **SPECIFICATION**

(Reference sheet)

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C220JB8NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22pF, 50V, ±5%, C0G, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>220</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	0603 (inch code)	L: 1.6 ± 0.1 mm	W: $0.8 \pm 0.1$ mm
	000		<b></b>
③ Dielectric	C0G	8 Inner electrode	Ni
Capacitance	<b>22</b> pF	Termination	Cu
⑤ Capacitance	±5 %	Plating	Sn 100% (Pb Free)
tolerance		Product	Normal
6 Rated Voltage	50 V	Special	Reserved for future use
⑦ Thickness	0.8 ± 0.1 mm	① Packaging	Cardboard Type, 7" reel

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition	
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms	
Q	840 min		
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.	
Resistance	Whichever is smaller		
Appearance	No abnormal exterior appearance	Microscope (×10)	
Withstanding	No dielectric breakdown or	300% of the rated voltage	
Voltage	mechanical breakdown		
Temperature	COG		
Characteristics	(From -55 ℃ to 125 ℃, Capacitance change should be within ±30PPM/℃)		
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.	
of Termination	terminal electrode		
Bending Strength	Capacitance change :	Bending to the limit (1mm)	
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.	
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder	
	is to be soldered newly	245±5℃, 3±0.3sec.	
		(preheating : 80~120 ℃ for 10~30sec.)	
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.	
Soldering heat	within ±2.5% or ±0.25pF whichever is larger		
	Tan δ, IR : initial spec.		

	Performance	Test condition
Vibration Test	Capacitance change :	Amplitude : 1.5mm
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)
Moisture	Capacitance change :	With rated voltage
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs
	Q: 173.33 min	
	IR: 500Mohm or 25Mohm $\cdot \mu$ F	
	Whichever is smaller	
High Temperature	Capacitance change :	With 200% of the rated voltage
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature
	Q: 330 min	1000+48/-0hrs
	IR: 1000Mohm or 50Mohm · μF	
	Whichever is smaller	
Temperature	Capacitance change :	1 cycle condition
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperature → 25°C
	Tan δ, IR : initial spec.	→ Max. operating temperature → 25°C
		5 cycle test

<sup>\*</sup> The reliability test condition can be replaced by the corresponding accelerated test condition.

## C. Recommended Soldering method:

Reflow ( Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.